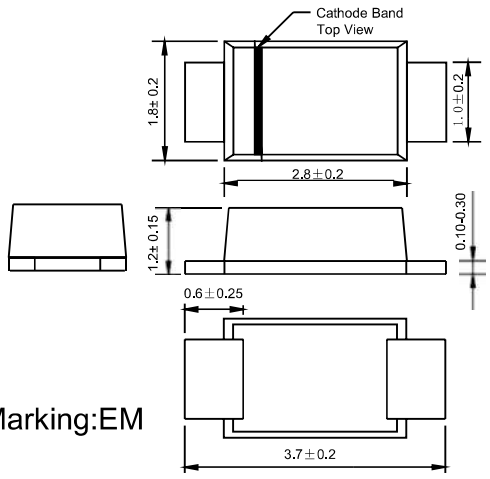
SOD1EM

SURFACE MOUNT SUPER FAST RECTIFIER

Reverse Voltage -1000Volts Forward Current - 1.0 Ampere

SOD-123FL



Marking:EM

Dimensions in millimeters

FEATURES

- Glass passivated device
- Ideal for surface mouted applications
- Low reverse leakage
- Metallurgically bonded construction
- High temperature soldering guaranteed:
  260℃/10 seconds,0.375"(9.5mm) lead length,
  5 lbs. (2.3kg) tension

MECHANICAL DATA

Case: JEDEC SOD-123FL molded plastic body
Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight:0.0007 ounce, 0.02 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

	SYMBOLS	SOD1EM	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	1000	VOLTS
Maximum RMS voltage	V_{RMS}	700	VOLTS
Maximum DC blocking voltage	V_{DC}	1000	VOLTS
Maximum average forward rectified current	$I_{(AV)}$	1.0	Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	25.0	Amps
Maximum instantaneous forward voltage at1.0A	V_F	1.7	Volts
Maximum DC reverse current T_A=25℃ at rated DC blocking voltage T_A=100℃	I_R	5.0 100.0	μA
Maximum reverse recovery time (NOTE 1)	trr	35	ns
Typical junction capacitance (NOTE 2)	C_J	10	pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	85	K/W
Operating junction and storage temperature range	T_J,T_{STG}	-55 to +150	°C

Note: 1.Measured with IF=0.5A, IR=1A, Irr=0.25A.
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3.PCB mounted on 0.2*0.2" (5.0*5.0mm) coppeer pad area.

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RATINGS AND CHARACTERISTIC CURVES

FIG. 1- FORWARD CURRENT DERATING CURVE

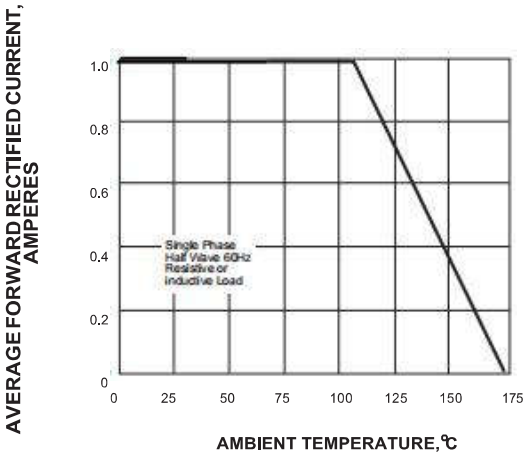

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

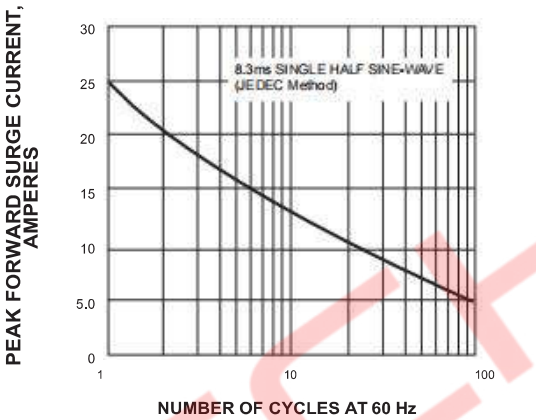

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

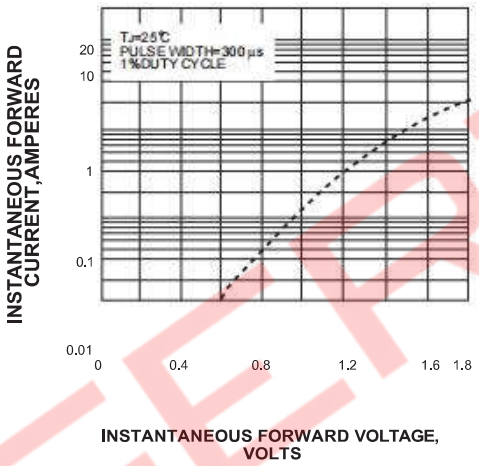

FIG. 4-TYPICAL REVERSE CHARACTERISTICS

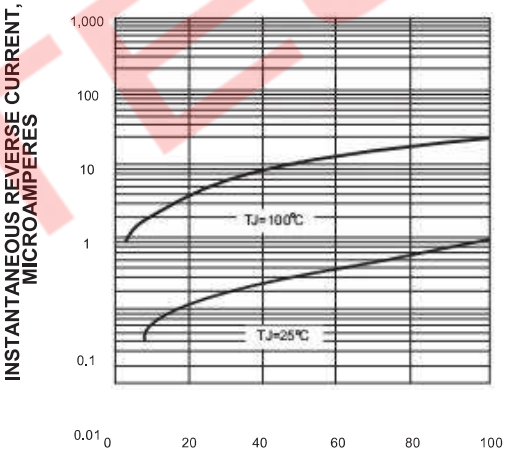

FIG. 5-TYPICAL JUNCTION CAPACITANCE

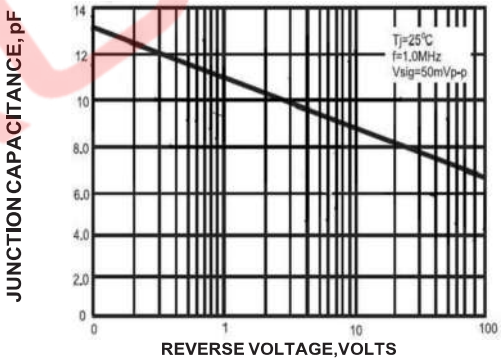

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE